

**SHARP**

SPEC No.	LH14Z01B
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To: \_\_\_\_\_

# S P E C I F I C A T I O N S

Product Type \_\_\_\_\_ Laser Diode \_\_\_\_\_

Model No. \_\_\_\_\_ **GH0631IA2GC** \_\_\_\_\_

※These specifications contain 11 pages including the cover and appendix.  
If you have any objections, please contact us before issuing purchasing order.

Accepted by: \_\_\_\_\_

By: \_\_\_\_\_

Name: \_\_\_\_\_

Title: \_\_\_\_\_

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Product name : Laser Diode

Model No. : GH0631IA2GC

1. These specification sheets include materials protected under copyright of Sharp Corporation ("Sharp"). Please do not reproduce or cause anyone to reproduce them without Sharp's consent.
2. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets, as well as the precautions mentioned below.  
Sharp assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets, and the precautions mentioned below.

(Precautions)

- (1) Please do verify the validity of this part after assembling it in customer's products, when customer wants to make catalogue and instruction manual based on the specification sheet of this part.
- (2) This product is designed for use in the following application areas ;

* OA equipment	* Audio visual equipment	* Home appliance
* Telecommunication equipment (Terminal)	* Measuring equipment	
* Tooling machines	* Computers	

If the use of the product in the above application areas is for equipment listed in paragraphs (3) or (4), please be sure to observe the precautions given in those respective paragraphs.
- (3) Appropriate measures, such as fail-safe design and redundant design considering the safety design of the overall system and equipment, should be taken to ensure reliability and safety when this product is used for equipment which demands high reliability and safety in function and precision, such as ;

* Transportation control and safety equipment (aircraft, train, automobile etc.)		
* Traffic signals	* Gas leakage sensor breakers	* Rescue and security equipment
* Other safety equipment		
- (4) Please do not use this product for equipment which require extremely high reliability and safety in function and precision, such as ;

* Space equipment	* Telecommunication equipment (for trunk lines)	
* Nuclear power control equipment	* Medical equipment	
- (5) Please contact and consult with a Sharp sales representative if four are any questions regarding interpretation of the above four paragraphs.

3. Please contact and consult with a Sharp sales representative for any questions about this product.

1. Scope

This specification covers the appearance and characteristics of red Laser Diode,  
Model No. GH0631IA2GC

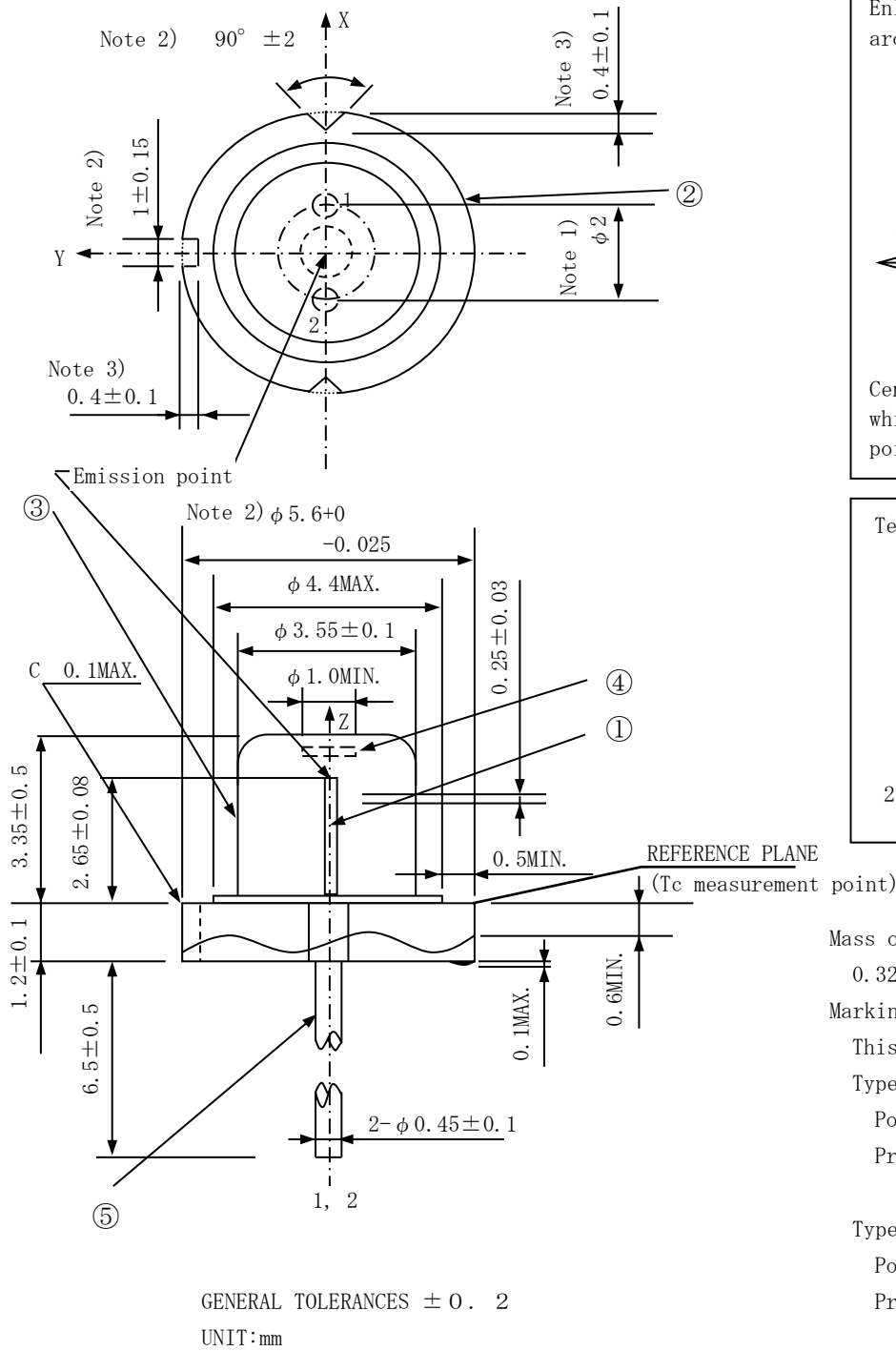
【Outline of this product】

This product is equipped with an GaInP multiple quantum well red laser diode .  
Oscillating transverse mode of this model is TE.  
This product is designed for a sensor, leader bar code and display light sources.

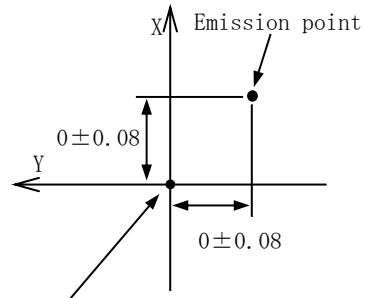
2. Outline Dimensions and Terminal Connections	described in page 2
3. Ratings and Characteristics	described in page 3
4. Reliability	described in page 4
5. Incoming inspection	described in page 5
6. Supplements	
6-1. ODS materials	described in page 5
6-2. RoHS compliant product	described in page 5
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6-6. Matters relating to disclaimers	described in page 8
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2. Outline dimensions and Terminal connections

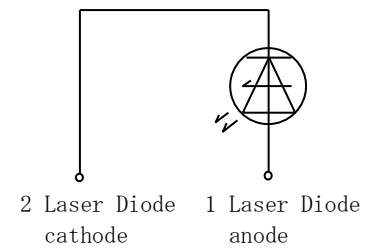


Enlarged drawing  
around the emission point



Center of the imaginary circle  
which goes through the three  
point around the stem

Terminal connections



Mass of the product :  
0.32g (reference value)

Marking  
This model has 2 way marking type.

Type. 1  
Position : Side of the cap  
Printed contents : 

1	2
3	4

  
(4 Character)

Type. 2  
Position : Bottom of the stem  
Printed contents : 

3	3	1	2	4	4
---	---	---	---	---	---

  
(6 Character)

Note 1) Dimension of the bottom of leads.  
Note 2) These dimensions are valid only in the range of 0 ~ 0.6mm  
below from the reference plane.  
Note 3) These dimensions are defined from the imaginary circle  
which goes through the three points around the stem to the bottom of cut off parts.

No.	Component	Material	Finish
①	Laser Diode Chip	AlGaInP/GaAs	-
②	Stem	Cu/Fe	Gold-plated
③	Cap	45 alloy	Nickel+Pd plated
④	Window glass	Borosilicated glass	Typ. n=1.52 (λp = 642nm)
⑤	Lead pins	Ni/Fe	Gold-plated

① Year of production  
② Month of production  
③ Model name  
④ Production lot

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## 3. Ratings and Characteristics

## 3-1 Absolute Maximum Ratings

(Tc=25°C (Note 1))

Parameter			Symbol	Value	Unit
Optical power output	CW	$-10^{\circ}\text{C} \leq T_c \leq 40^{\circ}\text{C}$	Po	185	mW
	CW	$40^{\circ}\text{C} < T_c \leq 60^{\circ}\text{C}$	Po	120	mW
Reverse voltage			Vr1	2	V
Operating temperature (Case temperature)			Top(c)	-10 ~ +60	°C
Storage temperature			Tstg	-40 ~ +85	°C
Soldering temperature (Note 2)			Tsld	350	°C

(Note 1) Tc : Case temperature

(Note 2) Soldering temperature means soldering iron tip temperature (The power 30W) while soldering.

Soldering position is 1.6mm apart from bottom edge of the case. (Immersion time:  $\leq 3\text{s}$ )

## 3-2 Electro-optical Characteristics

(Tc=25°C (Note 1))

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Threshold current	Ith	—	—	70	90	mA
Operating current	Iop	Po=180mW	—	215	240	mA
Operating voltage	Vop		—	2.55	3.0	V
Wavelength (Note 4)	$\lambda_p$		635	638	643	nm
Half Intensity Angle(Parallel) (Note 2, 3)	$\theta_{//}$		4	8	12	°
Half Intensity Angle(Perpendicular) (Note 2, 3)	$\theta_{\perp}$		8	13	18	°
Misalignment angle (Parallel) (Note 3)	$\Delta \theta_{//}$		-5	—	5	°
Misalignment angle (Perpendicular) (Note 3)	$\Delta \theta_{\perp}$		-5	—	5	°
Differential efficiency	$\eta_d$	$\frac{150\text{mW}}{I(180\text{mW}) - I(30\text{mW})}$	0.9	1.15	—	mW/mA

(Note 1) Initial value, Continuous Wave Operation

(Note 2) Angle of 50% peak intensity (Full angle at half-maximum)

(Note 3) Parallel to the junction plane(X-Z plane)

Perpendicular to the junction plane(Y-Z plane)

(Note 4) It is based on method for measurement of light spectrum analyzer Q8344A

made by Advantest Corp. of Sharp Corp. property.

4. Reliability  
4-1 The reliability of products satisfy all the items listed below.  
Reference Standards : JIS

Confidence level : 90%

No.	Test	Test Conditions	Samples:n	Defective:C	LTPD(%)	Failure criteria No. [4-2]
1	Solderability	Soldering temperature: 240±5℃ (Flux used) Immersion time:5±0.5s	11	0	20	1
2	Resistance to soldering	Soldering iron tip temperature:350+0℃/-5℃ Immersion time:3+0s/-1s (Note 1)	11	0	20	3, 4, 5
3	Terminal strength (Tensile test)	Load:5N Duration:5±1s Once for each terminal	11	0	20	2
4	Terminal strength (Bending test)	Load:2.5N 0° ~90° ~ 0° ~ -90° ~0° Once for each terminal	11	0	20	2
5	Mechanical shock	Acceleration:1,000m/s <sup>2</sup> Pulse width:6ms Direction:±X, ±Y and ±Z Three times for each direction	11	0	20	3, 4, 5
6	Variable frequency vibration	Acceleration:100m/s <sup>2</sup> or Amplitude:1.5mm Frequency: 10~500~10Hz 15min reciprocation Direction: X, Y and Z 2 h for each direction	11	0	20	3, 4, 5
7	Temperature cycling	Lower temperature:-40℃ Higher temperature:+85℃ Duration:30min each, 30 times	11	0	20	3, 4, 5
8	High temperature storage	Storage temperature:85℃ t=500 h	11	0	20	3, 4, 5
9	Low temperature storage	Storage temperature:-40℃ t=500 h	11	0	20	3, 4, 5
10	High temperature Humid atmosphere storage	Storage temperature:40℃ (Note 2) humidity:90%RH t=100h	11	0	20	3, 4, 5

(Note 1) Soldering position is 1.6mm apart from bottom edge of the case.  
(Note 2) To be measured after 72 hours exposure to the room atmosphere.

4-2 Parameters to be measured and Failure criteria

No.	Parameters	Failure judgment criteria
1	Solderability	95% or more is covered with solder.
2	Terminal strength	It is defective if there are breaking and loosening.
3	Threshold current	I <sub>th</sub> > initial value ×1.3, I <sub>th</sub> < initial value ×0.7
4	Operating current	I <sub>op</sub> > initial value ×1.3, I <sub>op</sub> < initial value ×0.7
5	Operating voltage	V <sub>op</sub> > initial value ×1.2, V <sub>op</sub> < initial value ×0.8

4-3 Lifetime Test  
The target mean time to failure (MTTF) of this product is more than 2,000h. MTTF is confirmed by performing the operating test under the following conditions in time of development or change process related to the reliability of this product.  
Samples tested should have a laser diode chip with the same structure of this model.

Conditions	Failure judgment criteria
T <sub>c</sub> =60℃, P <sub>p</sub> =120mW, APC drive (Note 2) 500 heures	Failure is defined as the time under the operating current under the conditions in the left changes 30% of the initial (12 h) value. (Note 1) As for the samples which do not fail within 500 hours, their life time is calculated by extrapolating operating current data of between 400 and 500hours. MTTF is estimated by plotting each life time in Weibull function worksheet.

(Note 1) Defective samples caused by surge current is rejected.  
(Note 2) Auto power control

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5. Incoming inspection

5-1 Inspection standards                    ISO 2859 single sampling plan

5-2 Inspection level                        S-2 normal inspection

5-3 AQL

5-3-1 Definition of the lot            the day shipping the product

5-3-2 Characteristics (Note 1)

AQL	Parameter	Failure judgment criteria
1.0	Ith, Iop, Vop, $\eta$ d, $\lambda$ p, $\theta$ //, $\theta \perp$ , $\Delta \theta$ //, $\Delta \theta \perp$	Not conforming to the specifications

(Note 1) Inspection is performed after blowing.

5-3-3 Appearance

AQL	Failure judgment criteria
1.0	Crack is found on the window glass.  Marking is not sufficiently clear to read.  Bent lead can not be restored.  Impurity or dust its size is over $50\mu\text{m} \times 50\mu\text{m}$ is found within $0.5\text{mm}\phi$ to the center of the window glass. (Note.2)
2.5	Diameter of stem is not conforming the specification

(Note2) Inspection is performed after blowing.

6. Supplements

6-1 ODS materials

This product shall not contain the following materials. Also, the following materials shall not be used in the production process for this product.

Materials for ODS : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methyl chloroform)

6-2 RoHS compliant product

This product complies with the RoHS Directive (2011/65/EU) and manufactured in accordance with Sharp's Green Device Guidelines.

6-3 Information relating to China RoHS.

Product Information Notification based on Chinese law, Management Methods for Controlling Pollution by Electronic Information Products.

Names and Contents of the Toxic and Hazardous Substances or Elements in the Product

Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent Chromium (Cr(VI))	Polybrominated Biphenyls (PBB)	Polybrominated Diphenyl Ethers (PBDE)
○	○	○	○	○	○
This table was created pursuant to the provisions of SJ / T 11364.  ○ : indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in GB/T26572.  × : indicates that the content of the toxic and hazardous substance in at least one homogeneous material of the part exceeds the concentration limit requirement as described in GB/T26572 standard.					

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6-4. Packing (Type. 1)

Note) This model has 2 way packing type. This packing method is applied to GH0631IA2GC made in Taiwan.

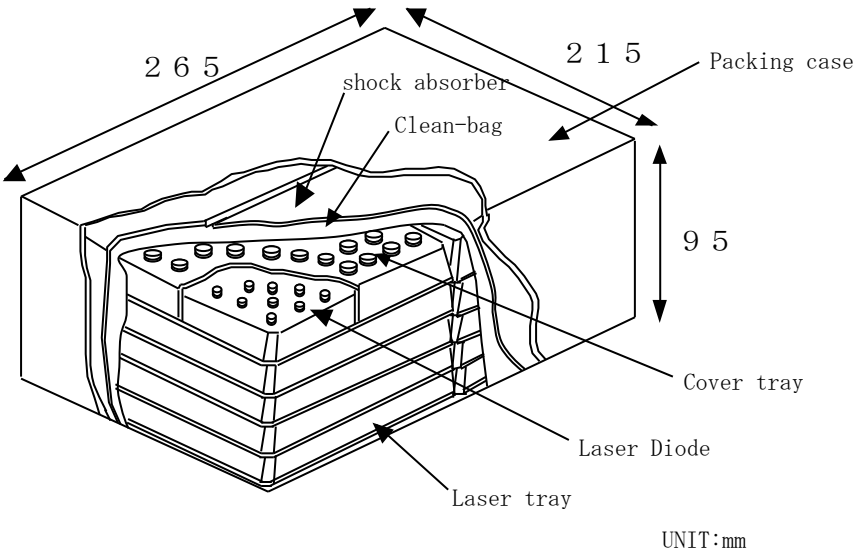
6-4-1. Packing method

- (1) Laser diodes are arranged in a laser tray.
- (2) One tray can accommodate 200 lasers. 5 trays wherein the laser diodes are arranged are stacked up.
- (3) A cover tray is stacked as a cover on the tray wherein the laser diodes are arranged. Stacked trays including a cover are bound with adhesive tape.
- (4) The above bound trays are stuffed into a clean-bag. The bag is sealed by dissolving thermally.
- (5) The trays in the bag are put into a packing case. One packing case can accommodate 2,000 lasers maximum, which is the minimum unit of packing. A Label where in the model number ,quantity and lot number are printed is stuck on both of the bag and the case(Refer to 6-4-4).

6-4-2. Materials for packing

No.	Component parts	Material
1	Laser tray	conductive polystyrene resin
2	Cover tray	conductive polystyrene resin
3	Clean-bag	anti - static plastic
4	Packing case	cardboard
5	shock absorber	anti - static polyetyrene

6-4-3. External appearance of packing



6-4-4. Label

(1)A label on the clean-bag

TYPE	Model name (Note 2)
Q'TY	1000
LOT	Lot No.

SHARP CORPORATION  
MADE IN \*\*\*\*(Note 1), **R.C.**  
(Note 3)

(2)A label on the packing case

TYPE	Model name (Note 2)
Q'TY	2000
LOT	Lot No.

SHARP CORPORATION  
MADE IN \*\*\*\*(Note 1), **R.C.**  
(Note 3)

- (Note 1) \*\*\*\*:Production country
- (Note 2) A management number in the factory is written in ( ), if the product produced in a factory except Japan.
- (Note 3) This identification mark shows the settlement product for RoHS designed by using a green material based on our green device guideline.



6-5. Packing (Type. 2)

Note) This model has 2 way packing type. This packing method is applied to GH0631IA2GC made in Japan.

6-5-1. Packing method

(1) Laser diodes are arranged in a laser tray.

(2) One tray can accommodate 250 lasers. 4 trays wherein the laser diodes are arranged are stacked up.

(3) The empty tray and the tray cover is stacked as a cover on the tray wherein the laser diodes are arranged.

Stacked trays including a cover are bound with adhesive tape.

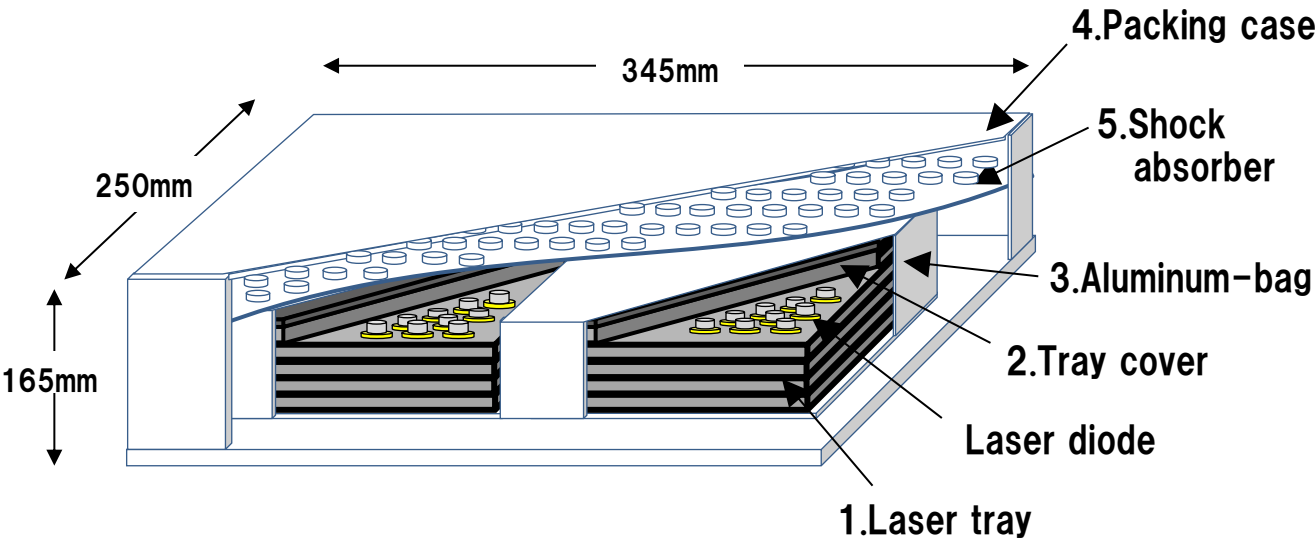
(4) The above bound trays are stuffed into a Aluminum-bag. The bag is sealed by dissolving thermally.

(5) 2 bags stuffed with trays is accommodated in a packing case. One packing case can accommodate 2,000 lasers maximum, which is the minimum unit of packing. A Label where in the model number, quantity and lot number are printed is stuck on both of the bag and the case(Refer to 6-5-4).

6-5-2. Materials for packing

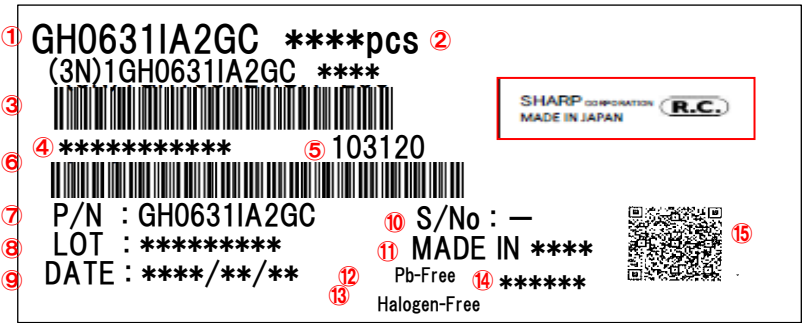
No.	Component parts	Material
1	Laser tray	conductive polystyrene resin
2	Tray cover	conductive polystyrene resin
3	Aluminum-bag	Aluminum
4	Packing case	cardboard
5	Shock absorber	anti - static polyetyrene

6-5-3. External appearance of packing



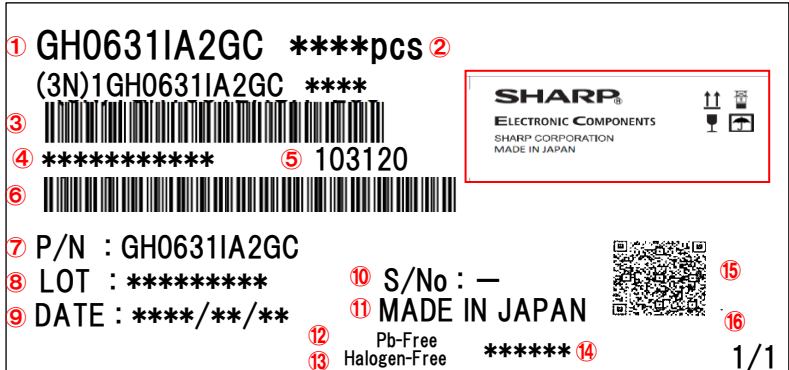
6-5-4. Label

(1)A label on the aluminum-bag



- ◆Label description
- ① : Model No.
  - ② : Quantity
  - ③ : 1st bar code:
  - ④ : Serial No (BOX-ID)
  - ⑤ : Company code (Sharp : 103120)
  - ⑥ : 2nd bar code:
  - ⑦ : Individual model No
  - ⑧ : Shipment lot
  - ⑨ : Printing date
  - ⑩ : Standard
  - ⑪ : Country of origin
  - ⑫ : Pb-free display
  - ⑬ : Halogen-free display
  - ⑭ : Label design
  - ⑮ : 2-dimensional bar code
  - ⑯ : Box fraction

(2)A label on the packing case



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## 6-6. Matters relating to disclaimers

The following contents related to failure and accident of this product,  
we do not assume the responsibility.

- (1) Due to the storage deficiencies in the inventory period on sales channels
- (2) Due to willful, negligence, handling failure
- (3) Due to this product connection or mounted equipment
- (4) Due to natural disasters, fire, water damage or, the disaster analogous thereto
- (5) Due to external factors such as abnormal voltage, abnormal electromagnetic waves,  
and catch fire, etc.
- (6) Due to the special environment (factory, coastal area, hot spring area, etc.)
- (7) Due to mounting deficiencies
- (8) Due to the repair of this product
- (9) Other things due to those not included in the product specification

## 7. Operating and handling precautions

- (1) This product has its life. The product life which is described in "Reliability" should be taken into account when using it.
- (2) This product will be damaged by electrostatic discharge(ESD). Following precautions should be taken to avoid ESD damage.
  - ⇒ Workers, workbenches and other equipment should always be grounded. Workers should always wear an antistatic wrist strap and an antistatic smock on them.
  - ⇒ When handling this product, workers should always wear antistatic gloves or finger covers.
  - ⇒ A stable DC power supply which is free from electrical transients should always be used when operating this product. A slow starter circuit should always be inserted between the power supply and this product in order to protect it from DC power surges.
  - ⇒ Optical power output of this product should be set with a highly reliable and high quality variable resistance.
  - ⇒ This product should always be connected to the driving circuit by soldering directly or through highly reliable connectors.
  - ⇒ While this product is being operated, be sure to avoid touching the driving circuit or the terminals of this product with electrical probes from a synchroscope or a voltmeter.
  - ⇒ An antistatic package should be used when storing this product.
  - ⇒ This product should be processed in the rooms where relative humidity is kept at 50-70%RH.
- (3) This product doesn't do the design that intends use in the following, special environment.  
Please use it after confirming the performance and reliability, etc. enough in your company before use in the following special environment.
  - ⇒ Use in place where a lot of moisture, be dewys, sea breezes, or causticity gases (Cl, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>x</sub>, etc.) exist.
  - ⇒ Use under direct sunshine, in out-of-door exposure, or in dust.
  - ⇒ Use in atmosphere such as water, oil, drug solutions, or organic solvents.
  - ⇒ Use in environment with strong static electricity or electromagnetic radiation.
  - ⇒ Use in state installed near generation of heat parts or in state to arrange combustible near this product.
- (4) Because the adhesion of garbage and dust to the window glass might disarrange an optical characteristic of this product, maintain the work room to cleanness so as not generate dust, please.
- (5) In this Product, generation of heat happens in the laser chip because of operating.  
The case temperature rises by this generation of heat. Because the rise of the case temperature becomes a factor to shorten the lifetime of this product, a sufficient heat sink should be attached to this product when operating so that its case temperature is to be maintained at the same level as that of the surrounding.

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## 7. Operating and handling precautions

- (6) Even if the drive current supply has an automatic power control (APC), automatic current control (ACC), or both, be sure to monitor the optical power output with an optical power meter while setting it. Never estimate the optical power output only from the drive current because it is likely to be decreased by temperature rise of the surrounding.
- (7) When dirt adheres to the window glass of this product, please wipe lightly with the cotton bud that adheres the ethanol.
- (8) The window glass cracks easily because it is thin. Therefore, please avoid putting the load on the cap, for example clumping, tightens, or fixing to the treatment device hard.
- (9) Since laser beam from this product will be harmful to the human eyes, the following precautions should be taken.
  - ⇒ When this product is being operated, the emitting surface of a chip should not be viewed either directly or through a lens, microscope or optical fibers.
  - ⇒ When operating this product, wear safety glasses.
- (10) When soldering this product, heat lead pins only using a soldering iron in short time. Avoid heat the whole package using pre-heat or reflow soldering.